

METHOD AND REDUCTION SOLUTION FOR METALLIZING A SURFACE

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Abstract of the Disclosure

10 A method for metallizing selected areas of a two dielectric layered sequentially processed circuit board (100) involves exposing the resin A (204) by photo-definition. The resin A (204) contains 10% or less, by weight Cu_2O particles (300) mixed uniformly throughout the resin. The circuit board (100) is sprayed with a reduction solution to form catalytic islands (301) predominately of Cu^0 or CuH . The circuit board (100) is then electrolessly plated to form conductors, pads or vias, where the resin A
15 (204) has been exposed. The reduction solution includes a primary reducing agent, a secondary reducing agent and a capturing agent. The reduction solution preferably has a pH of 10 or greater. The primary reducing agent is preferably a borohydride. The secondary reducing agent is preferably an iodide and the capturing agent is a chelating agent
20 preferably EDTA.

This Sheet Has Been Replaced

